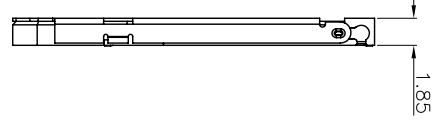
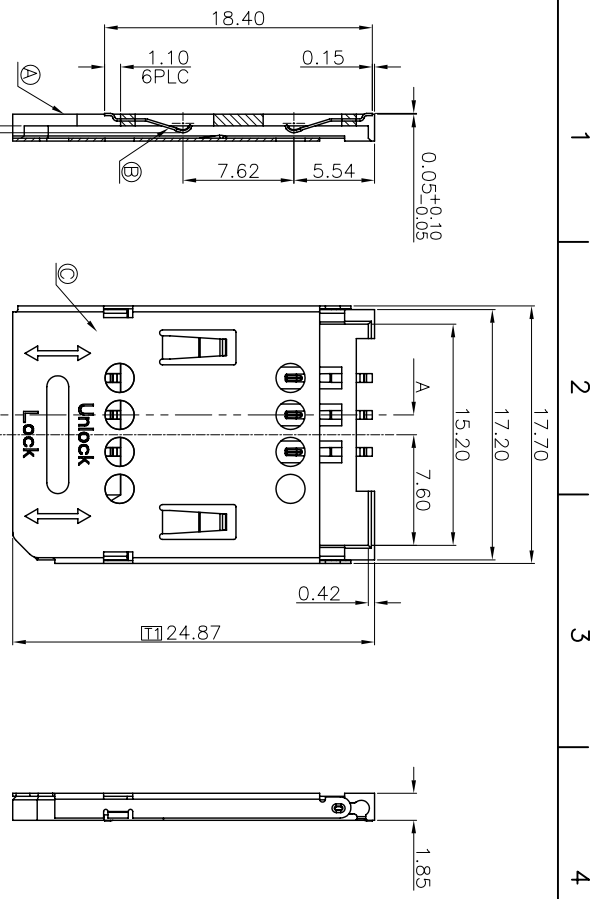
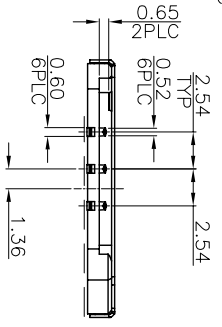


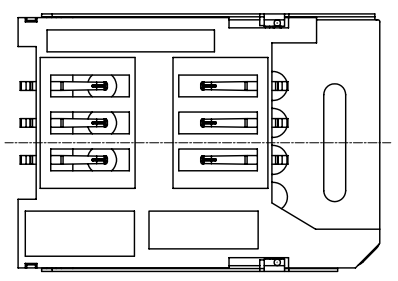
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	JUN HIA	8/3/07



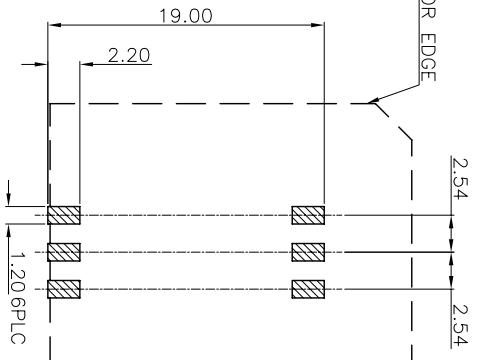
SECTION A-A



CONNECTOR EDGE  
(ALL LEADS)

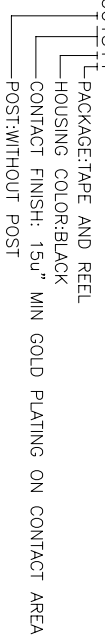


RECOMMENDED PC BOARD LAYOUT  
(TOL. ±0.05)(TOP VIEW)



NOTE:

1. MATERIAL:  
HOUSING:HIGH TEMP. THERMOPLASTIC;UL94V-0,COLOR BLACK.  
CONTACT:COPPER ALLOY,T=0.15;  
SHELL:STAINLESS STEEL,T=0.20.
2. FINISH:  
CONTACT:  
15u" MIN GOLD PLATING ON CONTACT AREA;  
1u" MIN GOLD PLATING ON SOLDER TAILS;  
50u"~180u" NICKEL UNDERPLATING OVERALL.
3. SPECIFICATION:SEE "HINGE SIM CARD PRODUCT SPEC."
4. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
5. TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE".
6. GREEN PRODUCT IDENTIFICATION IN PACKING: **[G.F. PASS]**
7. FOR REFLOW SOLDERING LEAD FREE PROCESS.
8. P/N DESCRIPTION:  
2SM2001-001511



9. D/C DESCRIPTION: YMMDD  
DAY MONTH YEAR

C	SHELL	1	STAINLESS STEEL,0.20T	UNPLATING
B	CONTACT	6	COPPER ALLOY,0.15T	SEE NOTES
A	HOUSING	1	HI-TEMP THERMOPLASTIC,UL94V-0	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING&COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS:	ANGLES:			
X :±0.5	X :±2°			
XX :±0.3	X.X :±1°			
XXX :±0.2				
TITEL	HINGE SIM CARD 1.85H			
DMW	JUN HIA	PART NO.	2SM2001-001511	
CHKD	8/3/07	SCALE:	N/A	
APVD	8/3/07	UNIT:	mm	
		SIZE:	A3	
		SHEET:	10F1	
		REV:	A	

Sington Electronic(Chung-Shan) Co., Ltd.  
信登電子(中山)有限公司

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